ERICSSON 💋

MAINTENANCE MANUAL 406-512 MHz RF ASSEMBLIES 19D417075G9-G38, 19B233690G1-G20 AND IF FILTER BOARDS 19C320523G2-G3, 19C331148G1-G2

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DESCRIPTION

The RF Assembly uses five tuned helical resonators to provide front end RF selectivity with no gain. A UHS preamplifier assembly is available that can be used with the receiver to improve sensitivity.

Mixer board A303 uses the RF signal from the RF Assembly and the mixer injection frequency from the oscillator multiplier board to generate the IF frequency.

CIRCUIT ANALYSIS

RF ASSEMBLY

Pre-Amplifier

The pre-amplifier is present only in UHS receivers, and uses a bi-polar transistor to provide approximately 10 dB gain.

RF from the antenna is link-coupled through helical resonator L2301 to the base of Class A pre-amplifier Q2301. L2301 matches the 50 ohm input to the base of Q2301. The amplified output is coupled through L2302, and connected through W2301 to J1 on Antenna Input Board A301. P2301 connects to J502 on the IF-Filter Board for regulated +10 Volt supply voltage.

Antenna Input A301A/A301B/A3O1C

An RF signal from the antenna or UHS pre-amplifier is applied to A301 which provides an AC ground between vehicle ground and receiver A-. Resistor R1 prevents a static charge from building up on the vehicle antenna. The output of A3O1 is coupled through five high Q helical resonators that provide the front end RF selectivity. The helicals are tuned to the in coming frequency by C301 through C305.

Mixer A304

The mixer uses a FET (Q1) as the active device. The FET mixer provides a high input impedance, high power gain and an output relatively free of harmonics (low in intermodulation products).

In the mixer stage, RF from the helical resonators is coupled through L1 and C2 which matches the RF output to the gate of mixer Q5O1. Injection voltage from the multiplier-selectivity stages is applied to the source of the mixer. The 11.2 MHz mixer IF output signal is coupled from the drain of Q1 through Cable W1 to J501 on the IF Filter board.



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IF FILTER

Crystal Filter

The output of A303-Q1 is coupled through a tuned circuit (L507 & C515) which matches the out put to the input of the four-pole monolithic crystal filter. The highly-selective crystal filter (FL501 & FL502) provides the first portion of the receiver IF selectivity. The output of the filter is coupled through impedance matching network L503 and C511 to the IF amplifier.

<u>Service Note:</u> Variable capacitor C504 does not require adjustment when performing normal alignment. If the four-pole monolithic crystal filter is replaced, then adjustment of C504 is necessary for optimum IF response.

IF Amplifier

IF Amplifier Q501 is a dual-gate FET. The filter output is applied to Gate 1 of the amplifier, and the output is taken from the drain. The biasing on Gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain. The output of Q501 is coupled through a network (L504 & C509) that matches the amplifier output to the crystal filter on the IFAS board. The output of the IF-Filter board is applied to the IFAS board through feed-through capacitor C325.

Supply voltage for the RF amplifier and IF-Filter board is supplied from the IFAS board through feed-through capacitor C326.

MODIFICATIONS

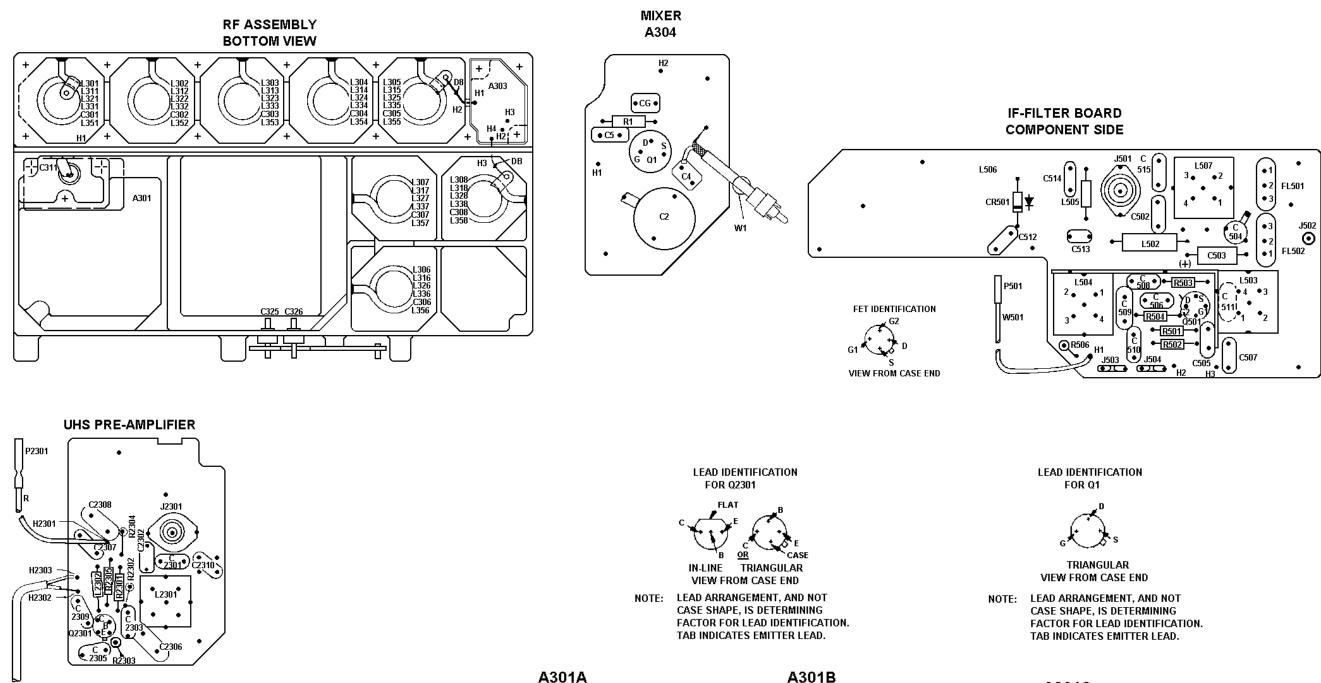
Some of the RF amplifier assemblies are not compatible with some of the IF-Filter boards without a modification to the RF assembly mixer board. Refer to the compatibility chart shown below.

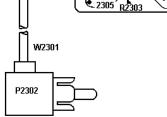
RF ASSEMBLY	COMPATIBLE WITH IF-FILTER BOARD
19D417075G9-G18	19C320523G2
19B233690G1-G10	19C331148G1

The following modifications are provided to permit field replacement using incompatible boards or assemblies. Refer to the applicable Outline Diagram for component location and printed wiring board layout.

- To modify RF assemblies 19D417075G9-G18 for operation with IF-Filter board 19C331148G1: add frequency select network Z1 from the drain of mixer FET Q1 to ground. Refer to the Parts List in this manual for the correct part number.
- To modify RF assemblies 19B233690G1-G10 for operation with IF-Filter board 19C320523G2: clip out and remove frequency select network Z1 on the mixer board.

LBI-30032



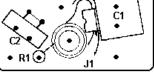


OUTLINE DIAGRAM 406-512 MHz, RF ASSEMBLY BOARD **19D417075G9-G18, IF FILTER BOARD** 19C320523G2 AND MIXER 19B227059G2

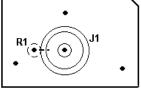
(19D423794, Rev. 10)

2

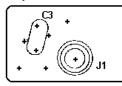
ANT INPUT (FLOATING GROUND)



A301B ANT INPUT (NON-FLOATING GROUND)

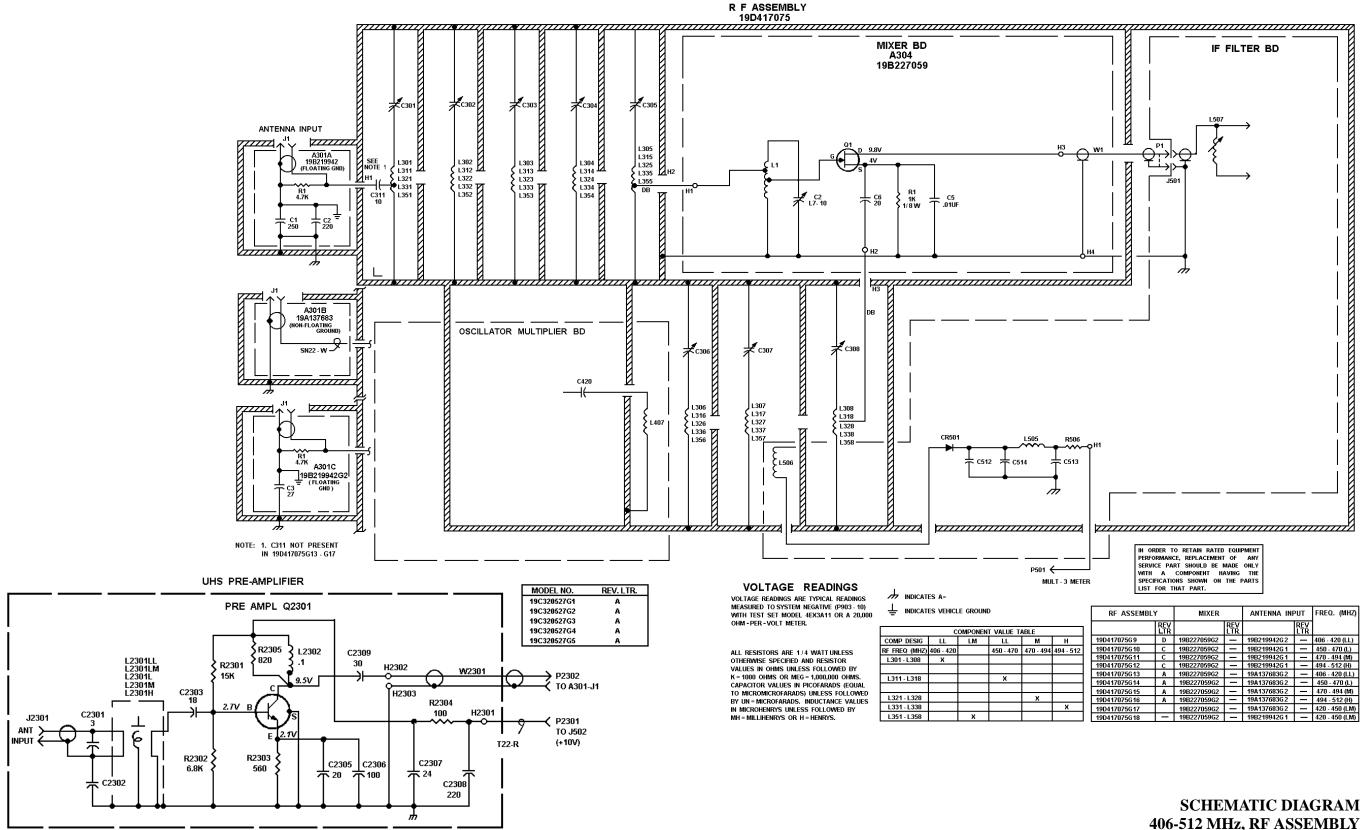


A301C ANT INPUT (FLOATING GROUND)





SCHEMATIC DIAGRAM



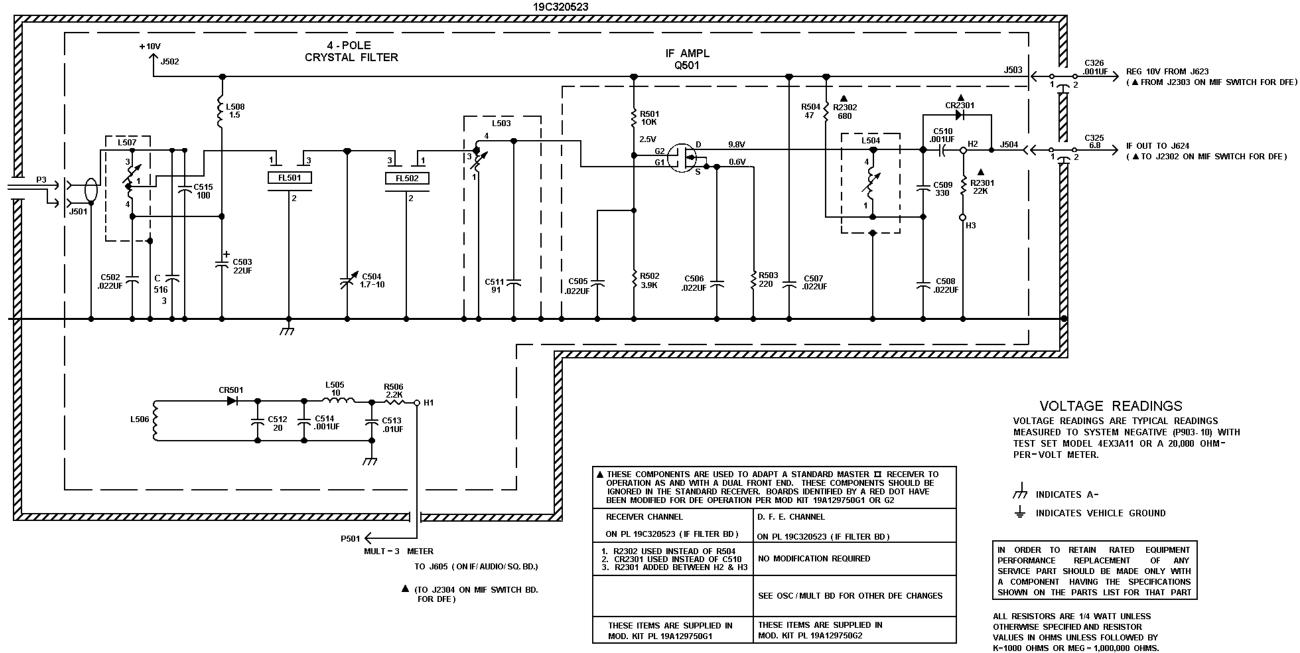
LBI-30032

406-512 MHz, RF ASSEMBLY

19D417075G9-G18 AND UHS PRE-AMPLIFIER 19C320527G1-5

(19D423520, Rev. 8), (19B226008, Rev. 7)

IF FILTER BD



rev Letter

Α

IF FILTER BD 19C320523G2

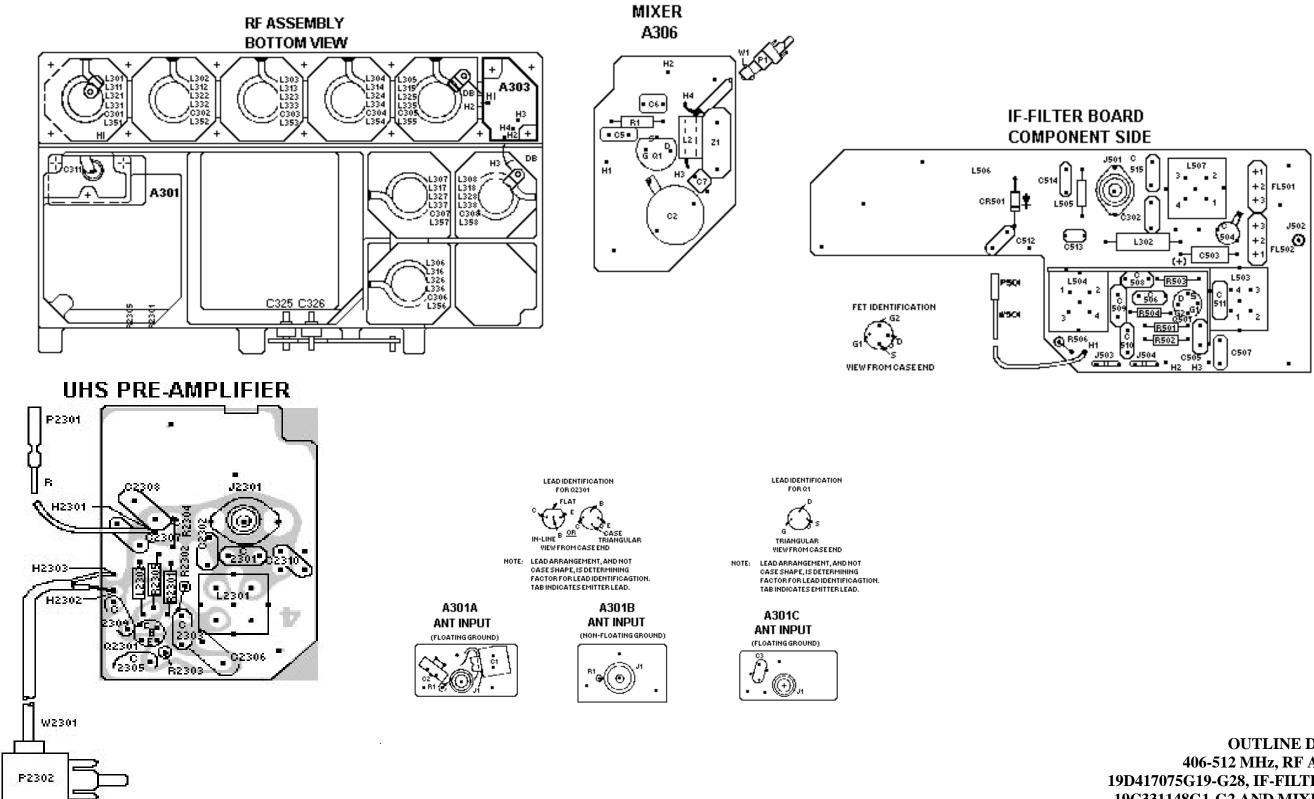
SCHEMATIC DIAGRAM **IF FILTER BOARD** 19C320523G2

(19D423519, Rev. 2)

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		CEMENT		
		BE MADE		
		THE SPI		
TH	E PARTS	LIST FOR	THAT	PART

CAPACITOR VALUES IN PICOFARADS (EQUAL TO MICROMICROFARADS) UNLESS FOLLOWED BY UF = MICROFARADS. INDUCTANCE VALUES IN MICROHENRYS UNLESS FOLLOWED BY MH = MILLIHENRYS OR H = HENRYS.

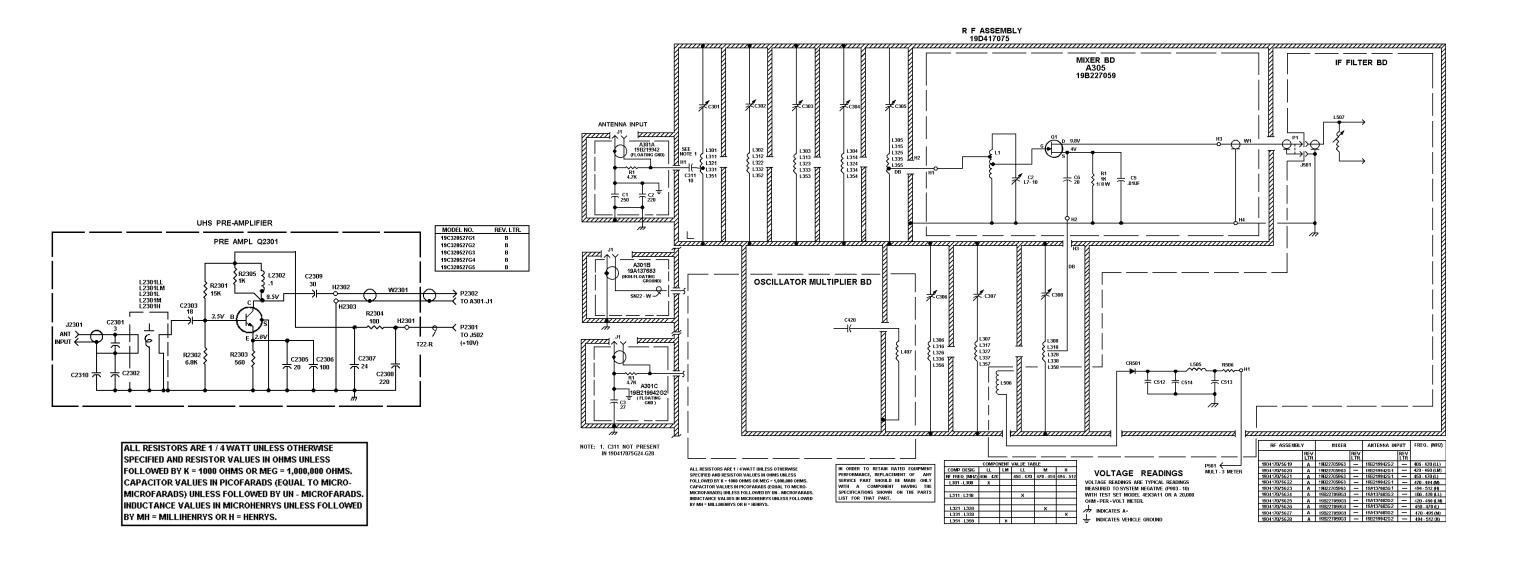
OUTLINE DIAGRAM



LBI-30032

OUTLINE DIAGRAMS 406-512 MHz, RF ASSEMBLY 19D417075G19-G28, IF-FILTER BOARD 19C331148G1-G2 AND MIXER BOARD 19B227059G3

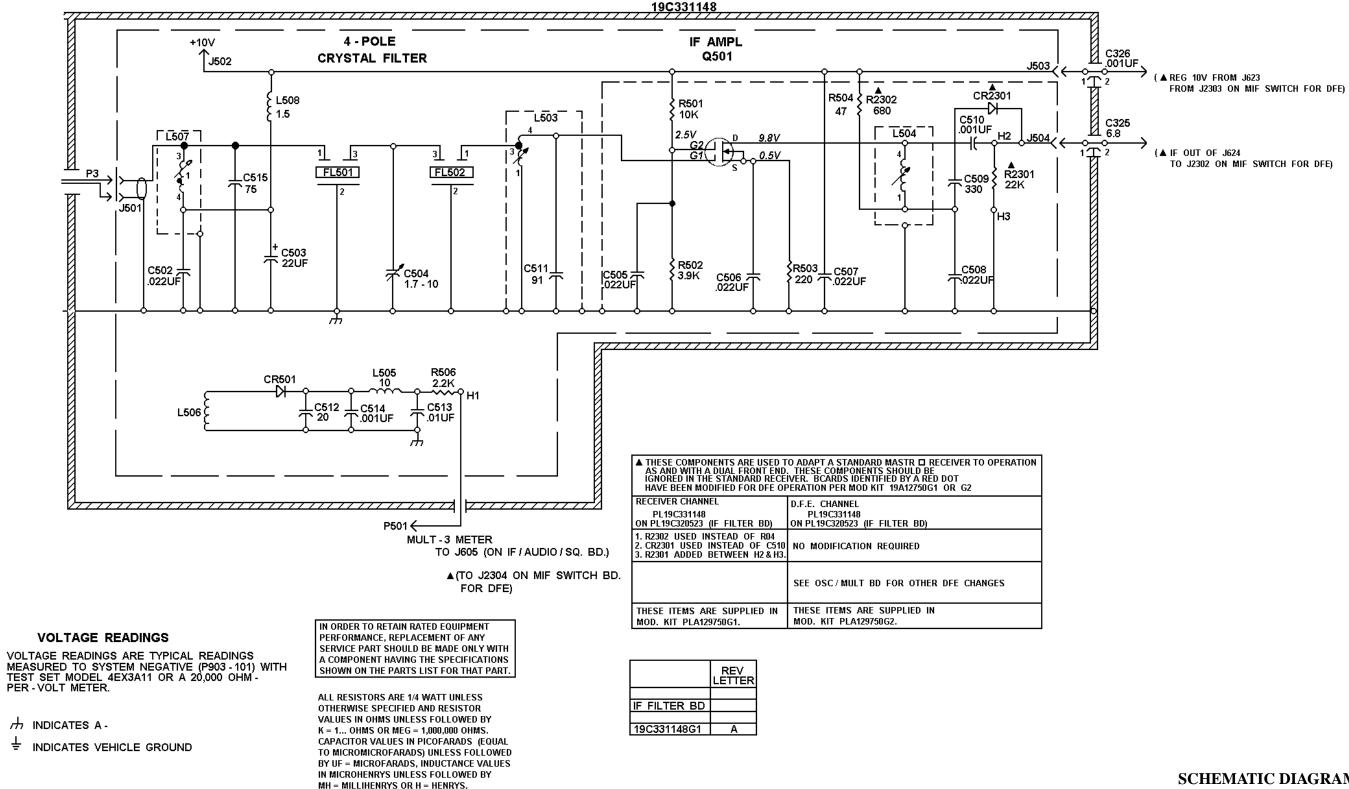
(19D433377, Rev. 0)



SCHEMATIC DIAGRAMS 406-512 MHz, RF ASSEMBLY 19D417075G19-G28 WITH MIXER BOARD 19B227059G3 AND UHS PRE-AMPLIFIER 19C320527G1-G5

(19D432485, Rev. 2), (19B226008, Rev. 8)

SCHEMATIC DIAGRAM

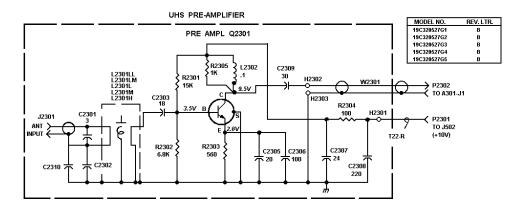


IF FILTER BD

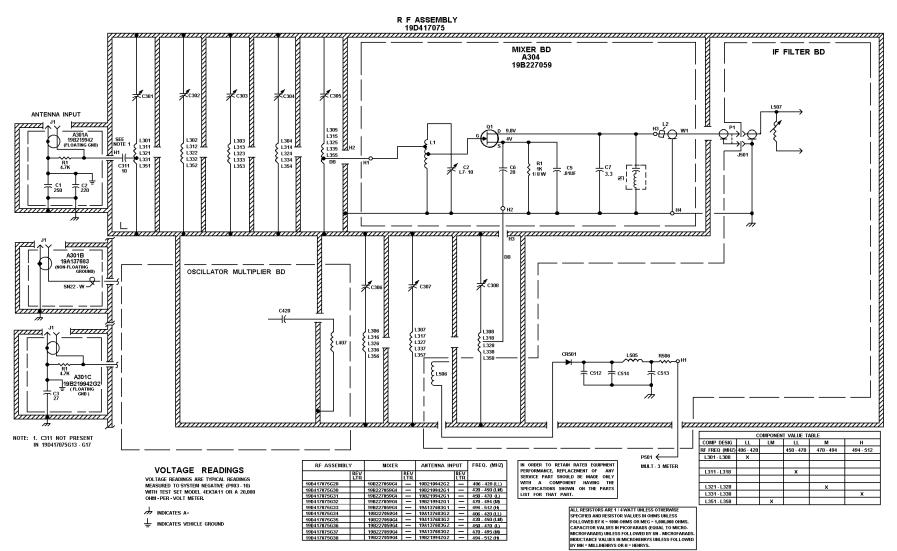
LBI-30032

SCHEMATIC DIAGRAM IF-FILTER BOARD 19C331148G1

(19D432484, Rev. 2)



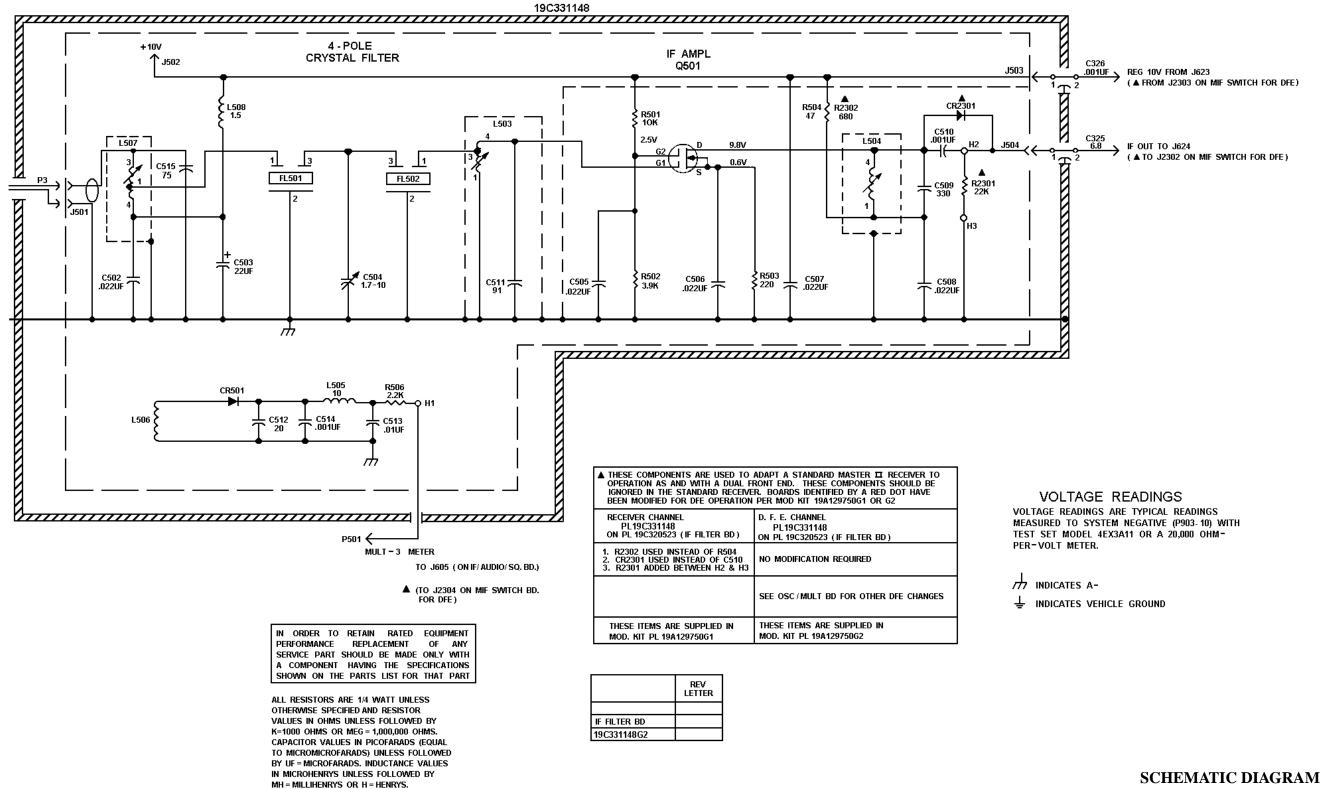
ALL RESISTORS ARE 1 / 4 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR VALUES IN OHMS UNLESS FOLLOWED BY K = 1000 OHMS OR MEG = 1,000,000 OHMS. CAPACITOR VALUES IN PICOFARADS (EQUAL TO MICRO-MICROFARADS) UNLESS FOLLOWED BY UN - MICROFARADS. INDUCTANCE VALUES IN MICROHENRYS UNLESS FOLLOWED BY MH = MILLIHENRYS OR H = HENRYS.



SCHEMATIC DIAGRAMS 406-512 MHz, RF ASSEMBLY 19D417075G29-G38 WITH MIXER BOARD 19B227059G4 AND UHS PRE-AMPLIFIER 19C320527G1-G5

(19D433368, Rev. 0), (19B226008, Rev. 8)

IF FILTER BD



LBI-30032

IF-FILTER BOARD 19C331148G2

(19D433378, Rev. 1)

		PARTS LIST	SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION
		LBIJOGJ2K 512 MHz Receiver RF Assembly						CABLES			IF FILTER BOARD 19C32052302, G3
	406-	IP-FILTER BOARD ASSEMBLY AND UHS PRE-AMPLIFIER	Li		Part of Printed Wiring Board 19D423518P1.	¥1	5491689P114	RF: approx. 5-1/8 inches long. (Includes Pi).			
					PLUGS			NETWORKS	C502	19470000529	Polyester: 0.022 uP ±10%, 50 VDCW.
SYMPOL		DESCRIPTION	P1		Part of W1.	Z1	19A134666P1	Frequency network: selective, 470-630 MHz res freq, 500 VDCW; sim to Dilectrou	C503	5496267P10	Tantalum: 22 uF +20%, 15 VDCW; sim to Sprague
SYMBOL	PART NO.	DESCRIPTION						TC501:NPO:240J:SLAC.	C504	19A700012P1	Type 150D. Variable, ceramic: 2 to 10 pF, 200 VDCW, temp
			Q1	19A134093P1	N Type, field effect; sim to Type 2N4391.	C301		Includes:	C505	194700005P9	coef -350+500 PPM; sim to Panasonic SCV-12W10X32.
		RF ASSEMBLY 19D417075G9 406-420 NHZ FLOATING GRD 19D417075G10 450-470 NHZ FLOATING GRD			RESISTORS	thru C305	19C328755P3	Screv.	thru C508	19470000599	Polyester: 0.022 uF <u>+</u> 20%, 50 VDCW.
		19D417075G11 470-494 MHz FLOATING GRD 19D417075G12 494-512 MHz FLOATING GRD	R1	3R151P102K	Composition: 1K ohms ±10%, 1/8 w.		194143476G2	Nut: thd. mize No. 6-32.	C509	5490008P139	Silver mica: 330 pF +10%, 500 VDCW, sim to
		19D417075G13 406-420 WHz NON FLOATING GRD 19D417075G14 450-470 WHz NON FLOATING GRD 19D417075G15 470-494 WHz NON FLOATING GRD			CABLES	C306 thru C308		Includes:	C510	19A116655P19	Electro Motive Type DM-15. Ceramic disc: 1000 pP +20%, 1000 VDCW; sim to
		19D417075G16 494-512 WHz NON FLOATING GRD 19D417075G17 420-450 WHz NON FLOATING GRD	¥1	5491689P114	RF: approx. 5-1/8 inches long.	2008	19C328755P2 19A143476G2	Screw. Nut: thd. mize No. 6-32.			RMC Type JF Discap.
		19D417075018 420-450 MHz FLOATING GRD 19D417075019 408-420 MHz FLOATING GRD - REV. A 19D417075020 450-470 MHz FLOATING GRD - REV. A	A 304 *		MIXER BOARD 198227059G2	C311+	5496218P241	Ceramic disc: 10 pP +5%, 500 VDCW, temp coef -80 PPM. Deleted by G13-G16 by REV A.	C511 C512	19A116656P20E0	(Part of L503). Ceramic disc: 20 pF ±10%, 500 VDCW, temp coef
		19D417075G21 470-494 MHz FLOATING GED - REV. A			(Added by REV. E)	C325	198209488P1	-80 PPM. Deleted by G13-G16 by RZV A. Coramic: 6.8 pF +20%, 500 VDCW; sim to Allen			O PPM.
A301A*		ANTENNA INPUT BOARD A301A 198219942G1 450-512 MRz (Deleted in G9			CAPACITORS			Bradley Style PASD.	C513 C514	194700005P7 194116655P20	Polyester: 0.01 uP ±10%, 50 VDCW.
A301C*		A301C 19B219942G2 406-420 MHz (Added to GP by	C2	19A700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPM; sim to Panasonic ECV-1ZW10X32.	C326	19B209488P2	Cernmic: 1000 pF -10+1005, 500 VDCW; sim Allen Bradley Style FASD.		188110655720	Ceramic disc: 1000 pF ±10%, 1000 VDCW; sim to BMC Type JF Discap.
		REV D).	C4+	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 FPM. Deleted in G9-G12 by REV C, in G13-G18 by REV A.			INDUCTORS	C5154	5490008P27	Silver mica: 100 pF +5%, 500 VDCW, sim to Slectro Motive Type DN-15.
		CAPACITORS	C5	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Erie 8121 Special.	L301	19B204938G37	Coil.	C515B	5490008P24	Silver mica: 75 pP $\pm 5\%$, 500 VDCW, sim to Electro Motive Type DM-15.
¢1	7484398P3	Silver mica: 250 pF ±10%, 500 VDCV; sim to Underwood Type 71HF.	C6	194700219P39	Ceramic: 20 pF ±5%, 100 VDCW, temp cost 0 PPM.	L302 thru	19B219944P1	Coil.	C516*	19A116656P3K0	Ceramic disc: 3 pF ±10%, 500 VDCW, temp coef
C2	19A116679P220K	Silver Mica: 220 pF +10%, 250 VDCV.			INDUCTORS	L304 L305	198204938G33	Co11.			0 PPM. Added by BEV A.
C3	19A116656P27J0	Ceramic disc: 27 pF ±5%, 500 VDC%, temp coef 0 PPM.	Lì		Part of Printed Board 19D42919491.	L306	19821994495	Coll.			DIODES AND RECTIPIERS
		JACKS AND RECEPTACLES			PLUGS	and L307			CR501	19A116052P1	Silicon, hot carrier: Fwd drop .350 wolts max.
J 1	7104941916	Jack, phono: coaxial; sim to National Tel Barrel Ceramic.	P1		Part of W1.	L308	19 8 204938641	Coil.			PILTERS
					TO 4201 0000 0	L311 L312	198204938G38	Coil.	FL501	19821957363	Crystal: Hesonator A - 11,200.000; Resonator B - 11,196.024 kHz.
R1	194700106979	RESISTORS	Q1	19A134093P1	N Type, field effect; sim to Type 2N4391.	thru L314	198219944P2	Co11.	FL502		(Part of FL501).
	194/001069/9	Composition: 4.7% ohms ±5%, 1/4 w.				1.325	198204938G34	Co11.			
A3018*		ANTENNA INPUT PLATE 19A137683C2	Rl	3R151P102J	Composition: 1K ohrs ±5%, 1/8 w.	L316 and	19821994496	Coil.	J501	194700049P2	Connector, receptacle: 500 VDCW maximum; sim to
		(Added to G13~G16 by REV. A)				L317 L318	1000000000		J502	4033513P1	NTTP-1058. Contact, electrical: sim to Bead Chain 193-4.
J 1	7104941920	JACKS AND RECEPTACLES	¥1	5491689P114	RF: approx. 5-1/8 foches long. (Includes P1).	L321	198204938G42 198204938G39	Coil.	J503 and	19 4 116975P1	Receptacle, wire spring.
	7104941920	Jack, phono: conxial.	A305			L322 thru	19B219944P3	Coil.	J504		
A301B*		ANTENNA INPUT PLATE 19A13768301 (Deloted to Clack by DEV A)	A303		KIXER BOARD 19822705963	L324					INDUCTORS
		(Deleted in G13-G16 by REV A)			CAPACITORS	L325 L326	19B204938G35	Coil.	L502*	7488079948	Coil, RF: 27 uH 10%, 1.4 ohms DC res max; sim. to Jeffers 4422-9. Deleted by REV A.
	2104041020	JACKS AND RECEPTACLES	C2	19A700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPM; sim to Panasonic ECV-12W10X32.	and L327	19B219944F7	Coil.	L503	19C320141G4	Coil. Includes:
J1	7104941920	Jack, phono: coaxial.	C5	19A116192P1	Ceramic: 0.01 uF ±20%, 50 VDCW; sim to Erie 8121	L328	198204938G43	Co11.	L504	5493185P9 19C320141G29	Tubing sing.
	101200100720	RESISTORS	C6	19A700219P39	Special. Ceramic: 20 pF ±5%, 100 VDCW, temp coef 0 FPM.	L331	19B204938G40	Coil.		5493185P9	Coil. Includes: Tuning slug.
R1	19A700106P79	Composition: 4.7K ohms <u>+</u> 5%, 1/4 w.	C7	194700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPM.	L332 thru	19B219944P4	Coil.	L505	194700024P25	Coil, RF: 10.0 uH ±10%, 3.70 ohms DC res max.
A303 *		WIXER BOARD 19822705961			INDUCTORS	L334 L395	198204938G36	Coil.	L506		(Part of Printed Board 19C320522P1).
		(Deleted by REV. B)	L1		Part of Printed Board 19D429194P1.	L336	19B219944P8	Coil.	L507	19C321810G1	Co11.
C1	19A116080P103	CAPACITORS	L2	194700122P1	Torridal core.	2nd L337			L508	19A700000P114	Coil, RP: 1.5 uH ±10%; sim to Jeffers 4412-7K.
с1 С2	19A116080P103 19A700012P1	Polyester: 0.022 uF ±10%, 50 VDCW. Variable, ceramic: 2 to 10 pF, 200 VDCW, temp			PLOGS	L338	19B204938G44	Coil.			PLIGS
		coef -350+500 PPM; sim to Panasonic ECV-12W10X32.	P1		Part of W1.	L351 L352	19B204938G47 19B219944P9	Coil. Coil.	P501		Part of W501.
c3	19A116656P2QKO	Ceramic disc: 20 pF ±10%. 500 VDCM, temp coef 0 PPM.				thru L354					
C4*	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, texp coef 0 PPH.	Q1	19A134093P1	N Type, field effect; sim to Type 2N4391.	L355	19B204938G48	Coil.	Q501	19A116818P1	N Channel, field effect.
	19A116656P3K0	Earlier than REV A: Ceramic disc: 3 pF <u>+</u> 10%, 500 VDCW, temp coei			RESISTORS	1356 and 1357	19B219944P10	Coil.			RESISTORS
		O PPM.	Rl	3R151Pt02J	Composition: 1K ohms $\pm 5\%$, 1/8 w.	L357 L358	198204938049	Coil.	R501	194700106987	Composition: 10K ones ±5%, 1/4 w.
									R502	19A700106P77	Composition: 3.0% ohms ±55, 1/4 e.
L											
*COMPON	ENTS ADDED, DE	LETED OR CHANGED BY PRODUCTION CHANGES		•	•	•					

SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION				SYMBOL	PART NO.	DESCRIPTION
R503	19A700106P47	Composition: 220 chms ±5%, 1/4 w.			TRANSISTORS			RF ASSEMBLY 19922369001-020			PLUGS
R504 R506	19A700106P31 19A700106P71	Composition: 47 ohms ±5%, 1/4 w.	Q2301	19A116859P2	Silicon, NPN.			ISSUE 4	P1		(Part of W1).
8306	154/00105/1	Composition: 2.2K obms ±5%, 1/4 w.			RESISTORS						TRANSISTORS
		CABLES	R2301	194700106P91	Composition: 15K ohms ±5%, 1/4 w.			1	Q1	19A134093P1	N Type, field effect; sim to Type 2N4391. (Used in G3).
¥501	19A129947G7	Cable: orange, No. 22 stranded, approx. 7-1/2 inches. (Includes P501).	R2302*	194700136P87	Composition: 10K ohms ±5%, 1/4 w.	SYMBOL	PART NO.	DESCRIPTION	Q1	19A700060P2	N Type, field effect. (Used in G4).
					In REV A & exclise:						RESISTORS
		UHS RF PRS-AMPLIFIER 19C320527G1 406-420 MHz (LL) 19C320527G2 450-470 MHz (L)	R2303	19A700106P83 19A700106P57	Composition: 6.8K ohms ±5%, 1/4 w.				R1	3R151P102J	Composition: 1K ohms ±5%, 1/8 w.
		19C320527G2 450-470 MBz (L) 19C320527G3 470-494 MBz (M) 19C320527G4 494-512 MHz (H)	R2303	194700106939	Composition: 560 ohms $\pm 5\%$, 1/4 w. Composition: 100 ohms $\pm 5\%$, 1/4 w.			STANDARD 198233690G1, 11 405-420 MHz 198233680G2, 12 420-450 MHz			
		19C320527G5 420-450 MHz (LM)	R2305*	19A700106P63	Composition: 1K ohms ±55, 1/4 w.			19B233690G3, 13 450-470 MHz 19B233690G4, 14 470-494 MHz		1001 (000014.4	
		CAPACITORS			In REV A:			198233690G5, 15 494-512 MHz	W1	4391689P114	Cable, RF: approx 5-1/2 inches long. (Includes P1).
C2301	19A116556P3J8	Ceramic disc: 3 pF ±0.5 pF, 500 VDCW, temp coef -80 PPM.		19A700106P61	Composition: 820 ohms ± 55 , 1/4 w. Added by REV A.			NON PLOATING GROUND CNLY 19823369066, 16 406-420 MHz			NETWORKS
C2302*	19A116679P220K	Silver Mica: 220 pF ±10%, 250 VDCW. Deleted by REV A.						198233690G7, 17 420-450 MHz 198233690G8, 18 450-470 MHz 198233880G9, 19 470-494 MHz	Z 1	19A134666P1	Frequency network: selective, 470-630 MHz res. freq, 500 VDCW; sim to Dilectron
C2302A*	19A134666P2	REV A. Frequency network: selective, 460-600 MHz res	W2301	5491689794	RF: approx. 3 inches long. (Includes P2302).			19823369009, 19 470-494 mHz 198233690610, 20 494-512 MHz			TC501:NPO:240J:SLAC.
		freq, 500 VDCW; sim to Dilectron TC501:NPO:270J:SLAC. Added by G1 & G5 by REV 4.						RP CIRCUIT			CAPACITORS
C2302B*	19A134666P1	Prequency network: selective, 470-630 MHz res freq, 500 VDCW; sim to Dilectrom		19550112161	Costing DE Cloude			19D417075G19, 29 406-420 MHz FLOATING GRD 19D417075G20, 30 420-450 MHz FLOATING GRD 19D417075G21, 31 450-470 MHz FLOATING GRD	C301 thru		Inçludes:
		TC501:NPO:240J:SLAC. Added to G2-G4 by REV A.		19822710161	Casting, RF Circuit. Cover, RF Circuit.			19D417075G22, 32 470-494 MRZ FLOATING GRD 19D417075G23, 33 494-512 MHZ FLOATING GRD	C305	19C328755P3	Screw.
C2303	19A116656P18J8	Ceramic disc: 18 pF ±5%, 500 VDCW, temp coef -80 PPM.		198209209P308	Tap screw, Phillips POZIDRIVE: No. 6-32 x 3/8.			19D417075G24, 34 408-420 MHz NON PLOATING GRD 19D417075G25, 35 420-450 MBz NON PLOATING GRD	C306	19A143476G2	Nut: thd. size No. 6-32. Includes:
C2305	19A116656P20K0	Ceramic disc: 20 pP ±10%, 500 VDCW, temp coef 0 PPM.		19032875593	(Secures RF Circuit Cover). Screw. (Part of C301-C305).			19D417075G28, 38 450-470 MHz NON PLOATING GRD 19D417075G27, 37 470-494 MHz NON FLOATING GRD 19D417075G28, 38 494-512 MHz NON FLOATING GRD	thru C308	19C328755P2	Screw.
C2306+	5490008P127	Silver mich: 100 pP ±10%, 500 VDCW, sim to		19C328755P2	Screw. (Part of C306-C308).					19A143476G2	Nut: thd. #1ze No. 6-32.
		Electro Motive Type DM-15.		19A143476G2	Nut: thd. size No. 6-32. (Part of C301-C308).	43014 and		COMPONENT BOARD A301A 199219942G1 A301C 199219942G1	C311	5496218P241	Ceramic disc: 10 pF ±5%, 500 VDCW, temp coef -80 FPM.
	19A116679P100K	Earlier than REV A: Silver Mica: 100 pF +10%, 250 VDCW,		403159491	Insulator. (Used with C504 on IF Filter Board).	A301C		X301C 198219842G1	C325	198209488P1	Ceramic: 6.8 pF ±20%, 500 VDCW; sim to Allen
C2307*	19A116656P24J0	Ceramic disc: 24 pP ±5%, 500 VDCW, temp coef		19821947022	Shield. (Used with IF Filter Board).				C326	19B209486P2	Bradley Style FASD. Ceramic: 1000 pF -10+100%, 500 VDCW; sim Allen
		0 PPM. Earlier than REV A:		19A129424G1 19A127(60P2	Can. (Used with L401~L403, L501, L503, L504). Can. (Used with L2301).	Cl	7484398P3	Silver mica: 250 pF ±10%, 500 VDCW; sim to Underwood Type 71HF.	020	156205400F2	Bradley Style PASD.
	19A116679P220K	Silver Mica: 220 pF ±10%, 250 VDCW.		4035306759	Useber, fiber. (Used with PL501, FL502).	C2	19A700015P37	Teflos/Mica: 220 pF ±5%, 250 VDCW.			INDUCTORS
C2308+	5490008P135	Silver mica: 220 pF +10%, 500 VDCW, sim to		403530(P23	Washer, fiber. (Used with J501, J2301).	C3	19A116656P27J0	Ceramic disc: 27 pP ±5%, 500 VDCW, temp coef 0 PPM.	L301	19B204938G37	Coil.
		Electro Motive Type DM-15. Earlier than REV A:		19A701332P1	Insulator disk. (Used with Q2301).			JACKS AND RECEPTACLES	L302 thru	198219944P1	Coil.
	19A116679P100K	Silver Mica: 100 pF ±10%, 250 VDCW.		403530(P11	Washer, fiber: 1/8 dis. (Used with Q501).	J1	7104841916	Jack, phono: conxial.	L304 L305	198204938633	Coil.
C2309	19A116656P30J8	Ceramic disc: 30 pF ±5%, 500 VDCW, temp coef		403530¢ P23	Washer, fiber. (Used with J501).				L305	198219944P5	Coll.
C2310*	19A116656P20E0	-80 PPM. Ceramic disc: 20 pF_±10%, 500 VDCW, temp coef				R1	194700108F79	Composition: 4.7K ohms ±5%, 1/4 w.	and L307		
		0 PPM. Deleted by REV A.							L308	198204938G41	Coil.
C2310A*	19A134666P2	Frequency network: selective, 480-700 MHz res freq, 500 VDCW; sim to Dilectron TC501:NPO:270J:SLAC. Added by REV B.				▲301B		ANTENNA INPUT PLATE 19A137883G2	L311	198204938G38	Co11.
C2310B*	19A134666P1	Frequency network: selective, 470-630 MHz res							L312 thru L314	19821994492	Co11.
		freq, 500 VDCW; sim to Dilectron TC501:NPO:240J:SLAC. Added by REV B.					7104941P20	JACKS AND RECEPTACLES JACKS AND RECEPTACLES Jack, phono: comminal.	L315	198204938634	Co11.
						J1	/104941720	JHCK, PHOLO. CORALKI.	L316	199219944P6	Coil.
J2301	19470004992	Connector, receptacle: 500 VDCW maximum; sim to				A305		MIXER BOARD	40d L317		
		NTTF-1058.						19822705963, 64	L318	19B204938G42	Coil.
		INDUCTORS							L321 L322	198204938G39 198219944P3	Coil. Coil.
1.2301LL 1.2301L	19D413078G3 19D413078G5	Helical resonator.				C2	194700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPM; sim to Panasonic ECV-1ZW10X32.	1.322 thru 1.324	10021004420	
L2301L L2301M	19D413078G5	Helical resonator.				C5	19A116192P1	Ceramic: 0.01 uF $\pm 20\%$, 50 VDCW; sim to Erie 8121 Special.	L325	198204938635	Coil.
L2301 H	19D413078G7	Helical resonator.				C6	19A700219P39	Ceramic: 20 pF ±5%, 100 VDCW, temp coef 0 PPM.	1326 and	198219944P7	Coil.
L23011.M	19D413078G9	Helical resonator.				C7	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPN.	L327		
L2302*	198209420P101	Coil, RF: .10 uH \pm 10%, 0.8 ohns DC res max; sim to Jeffers 4418-1K.						INDUCTORS	L328 L331	199204938G43 198204938G40	Coil.
		Errlier than REV A:				L1		(Part of Printed Board 19D429194P1).	L331 L332	198204938640 198219944P4	Coil.
	19A129716G4	Coil.				L2	194700122P1	Torridal core.	thru 1334		
		PLUGS									
P2301	19A702402P2	Contact, electrical; sim to AMP 42827-2.									
P2302		(Part of W2301).									
					1]	*COMPON	NENTS ADDED, D	ELETED OR CHANGED BY PRODUCTION CHANGES		1	1

PARTS LIST

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SYMBOL	PART NO.	DESCRIPTION	SYMBOL	
L335	198204938G36	Coil.		
L336 aud L337	19821994498	Coil.	Q501	1
L338	198204938644	Coil.		
L351	198204938647	Coil.	£501	
L352 tbru	198219944P9	Coil.	R502	
L354			R503	
1,355	198204938P48	Coil.	R504	
L356 101 1357	198219944F10	Coil.	R506	
L356	198204938P49	Co11.	₩501	;
		IF FILTER BOARD 19C331149C1 19C331148G2		
				3
C502	T644ACP322K	Polyester: 0.022 uF ±10%, 50 VDCW.		3
C503	19A701534P8	Tantalum: 22 uP ±20%, 16 VDCW.		
C504	194700012P1	Variable, ceramic: 2 to 10 pF, 200 VDCW, temp coef -350+500 PPM; sim to Panasonic ECV-12W10X32		
C505	194143477P17	Coel -350-500 PPm; Bim to PREBONIC ECV-12010832 Polyester: 0.22 uF ±20%, 50 VDCV.		
thru C506	1081434/1717	Foryester: 0.22 ar 220%, 30 VDCs.		:
C509	5490008P139	Silver mica: 330 pP ±10%, 500 VDCW, sim to Electro Motive Type DM-15.		
C510	194700233P7	Ceramic: 1000 pP ±20%, 50 VDCW.		
C511		(Part of L503).		
C512	19A116656P20K0	Ceramic disc: 20 pF ±10%, 500 VDCW, temp coef 0 PPM.		
C513	T644ACP310K	Polyester: .010 uF ±10%, 50 VDCW.		
C514	194700233P7	Cersmic: 1000 pF ±20%, 50 VDCW.		
515	5490008724	Silver mics: 75 pF \pm 5%, 500 VDCW, sim to Electro Notive Type DM-15.		
CR501	19470004791	DIODES AND RECTIFIERS		
	134100047FI			
FL501	19B219573G3	Crystal: Resonator A - 11,200.000; Resonator B -		
FL502		11,196.024 kHz. (Part of FL501).		
		JACKS AND RECEPTACLES		
J501	19A700049P2	Connector, receptacle: 500 VDCW maximum; sim to NTTF-1058.		
J502	4033513P1	Contact, electrical: sim to Bead Chain L93-4.		
3503 and 3504	19A116975P1	Contact, electrical.		
		INDUCTORS		
L503	19C320141G4	Coil. Includes:		
	5493185P9	Tuning slug.		
L504	190320141629	Coil. Includes;		
	5493185P9	Tuning slug.		
1505	19A700024P25	Coil, RF: 10.0 uH ±10%, 3.70 ohms DC res max.		
-506		(Part of Printed Board 19C331147P1).		
1507	19032181061	Coll.		
.508	19A7000009114	Coil, RF: 1.5 uH ±10%; sim to Jeffers 4412-7K.		
		PLUCS		
2501		(Part of ¥501).		
				1

19A116618P1	N Channel, field effect.
CONTROLOFI	« channel, tield effect.
	RESISTORS
19A700106P87	Composition: 10% ohms ±5%, 1/4 w.
19A700106P77	Composition: 3.9K ohms ±5%, 1/4 w.
194700106P47	Composition: 220 ohms ±5%, 1/4 w.
19A700106P31	Composition: 47 ohms ±5%, 1/4 w.
194700106971	Composition: 2.2K chmms ±5%, 1/4 w.
	CABLES
19412994767	Cable: orange, No. 22 stranded, approx. 7-1/2 inches. (Includes P501).
	MISCELLAREOUS
19E501121G1	Casting, RF Circuit.
19B227101G1	Cover, RF Circuit.
19B209209P306	Tap screw, Phillips POZIDRIY®: No. 6-32 x 3/8. (Secures RF Circuit Cover).
19C328755P3	Screw. (Part of C301-C305).
19C328755P2	Screw. (Part of C306-C308).
19A143476G2	Nut: thd. size No. 6-32. (Part of C301-C308).
4031594P1	Insulator. (Used with C504 on IF Filter Board).
198219470P2	Shield. (Dwed with IF Filter Board).
194129424G1	Cun. (Used with 1503, 1504, 1507).
4035306P59	Washer, fiber. (Used with FL501, FL502).
4035306723	Washer, fiber. (Dsed with J501).
4035306P11	Washer, fiber: 1/8 dia. (Used with Q501).
19A129715G1	Adapter Board.

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after all the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A - <u>RF Assembly 19D417075G0-12</u>

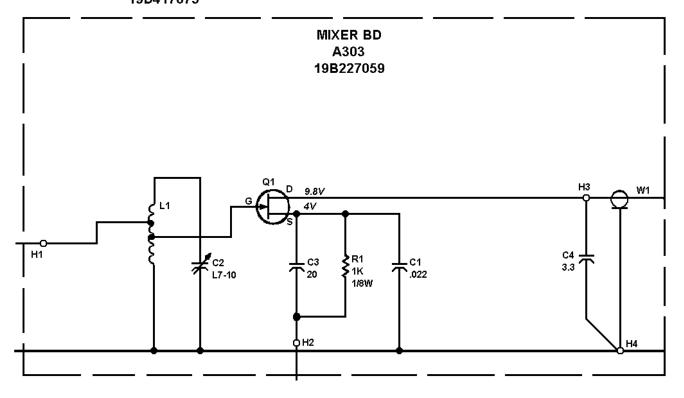
To improve receiver sensitivity. Changed C4.

REV. B - <u>RF Assembly 19D417075G0-12</u>

To incorporate new mixer board. Replaced A303 (19B227059G1) with A304 (19B227059G2).

Schematic Diagram Was:

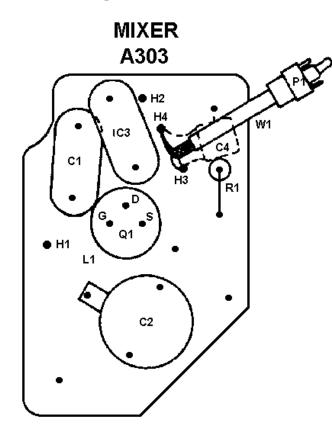
RF ASSEMBLY 19D417075



PARTS LIST

PRODUCTION CHANGES - (Continuation)

Outline Diagram Was:



- REV. A IF Filter Board 19C320523G2
 - To improve operation. Replaced L502 with L508, added C516.
- REV. A <u>RF Assembly 19D417075G13-G16</u>
- REV. C <u>RF Assembly 19D417075G9-G12</u> To improve sensitivity. Deleted A304-C4.
- REV. D <u>RF Assembly 19D417075G9</u> To improve receiver sensitivity in 406 to 420 MHz range. Added A301C.
- REV. A <u>UHS Pre-Amplifier</u> To incorporate new coil (L2302). Changed L2302, C2302, C2306, C2307 and C2308. Deleted C2310 and added R2305.
- REV. B <u>UHS Pre-Amplifier</u> To improve receiver sensitivity. Changed R2302 and R2305. Added C2310.
- REV. A <u>RF Assembly 19D417075G19-G28</u> IF Filter Board 19C331148G1
 - To improve operation of UHF mixer circuit. Added C7 and L2.
- REV. B UHS Pre-Amplifier

To improve receiver sensitivity. Changed R2302 and R2305. Added C2310.

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